

Application No. 12816-021001

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Applicant Detlef Weber

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U.S. Patent Documents							
Examiner Initial	Desig. ID	Patent Number	Issue Date	Patentee	Class	Subclass	Filing Date If Appropriate
	AA						
	AB						
	AC						
	AD				-		
	AE						
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	AH						
	AI						
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	AK						<u> </u>

Foreign Patent Documents or Published Foreign Patent Applications								
Examiner Initial	Desig. ID	Document	Publication	Country or			Trans	lation
Illiliai	טו	Number	Date	Patent Office	Class	Subclass	Yes	No
pc	AL	EP 0 989 609 A1	03/29/2000	EPO	H01L	23/522		
	AM							
	AN							
	AO						,	*****
	AP							-

Other Documents (include Author, Title, Date, and Place of Publication)					
Examiner	Desig.				
Initial	ID	Document			
PC	AQ	Rossnagel, S.M., "Filling dual damascene interconnect structures with AlCu and Cu using ionized magnetron deposition", J. Vac. Sci. Technol. B 13:125-129, (1995)			
J	AR				
•	AS				
	AT				

Examiner Signature	Date Considered ,				
PHAT Y- CAO	12/30/02				
EXAMINER: Initials citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.					